

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
FLIPCHIP INTERNATIONAL, LLC		10/12/2005	LIMITED LIABILITY COMPANY: DELAWARE

RECEIVING PARTY DATA

Name:	Wells Fargo Bank, National Association
Street Address:	100 Washington Street, 15th Floor
Internal Address:	Wells Fargo Plaza, MACS S4101-158
City:	Phoenix
State/Country:	ARIZONA
Postal Code:	85003
Entity Type:	National Association:

PROPERTY NUMBERS Total: 5

Property Type	Number	Word Mark
Serial Number:	78168486	SPHERON
Serial Number:	75347767	ULTRA CSP
Serial Number:	78439264	FOC FLEX-ON-CAP
Serial Number:	78428935	LIFESTYLE
Serial Number:	78428930	FLIPCHIP INTERNATIONAL

CORRESPONDENCE DATA

Fax Number: (602)229-5690
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 602-229-5228
 Email: hbuchta@quarles.com
 Correspondent Name: Heather L. Buchta, Esq.
 Address Line 1: Two North Central Avenue
 Address Line 2: One Renaissance Square
 Address Line 4: Phoenix, ARIZONA 85004

CH \$140.00 78168486

ATTORNEY DOCKET NUMBER:	153325.00012
NAME OF SUBMITTER:	Heather L. Buchta
Signature:	/Heather L. Buchta/
Date:	10/13/2005

Total Attachments: 15

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AMENDED AND RESTATED PATENT AND TRADEMARK SECURITY AGREEMENT

This Amended and Restated Patent and Trademark Security Agreement (this "Agreement"), dated as of October 12, 2005, is made by and between FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company having a business location at the address set forth below next to its signature (the "Debtor"), and WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division having a business location at the address set forth below next to its signature (the "Secured Party").

Recitals

The Debtor and the Secured Party are parties to a Credit and Security Agreement of even date herewith (as the same may hereafter be amended, supplemented or restated from time to time, the "Credit Agreement") setting forth the terms on which the Secured Party may now or hereafter extend credit to or for the account of the Debtor.

As a condition to extending credit to or for the account of the Debtor, the Secured Party has required the execution and delivery of this Agreement by the Debtor.

ACCORDINGLY, in consideration of the mutual covenants contained in the Loan Documents (as defined in the Credit Agreement) and herein, the parties hereby agree as follows:

1. Definitions. All terms defined in the Recitals hereto or in the Credit Agreement that are not otherwise defined herein shall have the meanings given to them therein. In addition, the following terms have the meanings set forth below:

"Event of Default" shall have the meaning given in Section 5.

"Obligations" means each and every debt, liability and obligation of every type and description arising under or in connection with any Loan Document (as defined in the Credit Agreement) which the Debtor may now or at any time hereafter owe to the Secured Party, whether such debt, liability or obligation now exists or is hereafter created or incurred and whether it is or may be direct or indirect, due or to become due, absolute or contingent, primary or secondary, liquidated or unliquidated, independent, joint, several or joint and several, and including specifically, but not limited to, the Obligations (as defined in the Credit Agreement).

"Patents" means all of the Debtor's right, title, interest and license rights in and to patents, applications for patents, and licensed Delphi Patents pursuant to the Technology Transfer Agreement (including, without limitation, any and all continuations, continuations-in-part, re-issues, divisions, extensions, substitutes, renewals, reexaminations and foreign counterparts thereof) and fees or royalties with respect to each, and including without limitation the right to sue for past

infringement and damages therefor, and licenses thereunder, all as presently existing or hereafter arising or acquired, including without limitation the patents listed on **Exhibit A**.

"Security Interest" has the meaning given to it in Section 2(a).

"Trademarks" means all of the Debtor's right, title and interest in and to: (i) trademarks, service marks, collective membership marks, registrations and applications for registration for each, and the respective goodwill associated with each, (ii) licenses, fees or royalties with respect to each, whether or not such trademarks, service marks, collective membership marks registered with any state, federal, or national government, (iii) the right to sue for past, present and future infringement, dilution and damages therefor, (iv) and licenses thereunder, all as presently existing or hereafter arising or acquired, including, without limitation, the marks listed on **Exhibit B**.

2. Security Interest.

(a) The Debtor hereby irrevocably pledges and assigns to, and grants the Secured Party a security interest (the "Security Interest"), with power of sale to the extent permitted by law, in the Patents and in the Trademarks to secure payment of the Obligations. As set forth in the Credit Agreement, the Security Interest is coupled with a security interest in substantially all of the personal property of the Debtor.

(b) The foregoing notwithstanding, and with respect to the grant of Security Interests hereunder only, the terms Patents and Trademarks shall not include the following "Excluded Collateral": Debtor's Patents and Trademarks, in each case subject to any agreement (A) the terms of which expressly prohibit the granting of a lien or an assignment with respect to such item and then only to the extent (i) any necessary consent shall not have been obtained and (ii) the terms of any such agreement are not in contravention of Section 9-408 of the Uniform Commercial Code, or (B) with respect to which the granting of liens and security interests therein would otherwise result in a loss of rights therein by operation of law. Debtor hereby represents and warrants to the Secured Party that the Excluded Collateral, when taken as a whole, is not material to the operations, business, properties or condition of Debtor.

3. Representations, Warranties and Agreements. The Debtor represents, warrants and agrees as follows:

(a) ***Existence; Authority.*** The Debtor is a limited liability company duly organized, validly existing and in good standing under the laws of its state of organization, and this Agreement has been duly and validly authorized by all necessary organizational action on the part of the Debtor.

(b) **Patents. Exhibit A** accurately lists all Patents owned or controlled by the Debtor as of the date hereof, or to which the Debtor has a right as of the date hereof to have assigned to it, and accurately reflects the existence and status of applications and letters patent pertaining to the Patents as of the date hereof. If after the date hereof, the Debtor owns, controls or has a right to have assigned to it any Patents not listed on Exhibit A, or if Exhibit A ceases to accurately reflect the existence and status of applications and letters patent pertaining to the Patents, then the Debtor shall within 60 days provide written notice to the Secured Party with a replacement Exhibit A, which upon acceptance by the Secured Party shall become part of this Agreement.

(c) **Trademarks. Exhibit B** accurately lists all Trademarks owned or controlled by the Debtor as of the date hereof and accurately reflects the existence and status of Trademarks and all applications and registrations pertaining thereto as of the date hereof; provided, however, that Exhibit B need not list common law marks (i.e., Trademarks for which there are no applications or registrations) which are not material to the Debtor's or any Affiliate's business(es). If after the date hereof, the Debtor owns or controls any Trademarks not listed on Exhibit B (other than common law marks which are not material to the Debtor's or any Affiliate's business(es)), or if Exhibit B ceases to accurately reflect the existence and status of applications and registrations pertaining to the Trademarks, then the Debtor shall promptly provide written notice to the Secured Party with a replacement Exhibit B, which upon acceptance by the Secured Party shall become part of this Agreement.

(d) **INTENTIONALLY LEFT BLANK.**

(e) **Title.** The Debtor has absolute title to each Patent and each Trademark listed on Exhibits A and B, free and clear of all Liens except Permitted Liens. The Debtor (i) will have, at the time the Debtor acquires any rights in Patents or Trademarks hereafter arising, absolute title to each such Patent or Trademark free and clear of all Liens except Permitted Liens, and (ii) will keep all Patents and Trademarks free and clear of all Liens except Permitted Liens.

(f) **No Sale.** Except as permitted by the terms Section 6.18 of the Credit Agreement, and Section 4 of this Agreement the Debtor will not assign, transfer, encumber or otherwise dispose of the Patents or Trademarks, or any interest therein, without the Secured Party's prior written consent.

(g) **Defense.** Except as permitted by the terms Section 6.14(a) of the Credit Agreement, the Debtor will at its own expense and using commercially reasonable efforts protect and defend the Patents and Trademarks against all claims or demands of all Persons other than those holding Permitted Liens.

(h) **Maintenance.** Unless, in the reasonable determination of the Debtor, (i) the maintenance costs of such Patents and Trademarks outweigh the usefulness of such Patents and Trademarks to the business of the Debtor and (ii) the loss of such Patents and Trademarks would not be disadvantageous in any material respect to the Lender, the Debtor will at its own expense maintain the Patents and the Trademarks, including, but not limited to, filing all applications to obtain letters patent or trademark registrations and all affidavits, maintenance fees, filing fees, annuities, and renewals possible with respect to letters patent, trademark registrations and applications therefor. The Debtor covenants that unless, in the reasonable determination of the Debtor, (i) the maintenance costs of such Patent or Trademark outweigh the usefulness of such Patent or Trademark to the business of the Debtor and (ii) the loss of such Patent or Trademark would not be disadvantageous in any material respect to the Lender, it will not abandon nor fail to pay any maintenance fee, filing fee or annuity due and payable on any Patent or Trademark, or fail to file any required affidavit or renewal in support thereof, without first providing the Secured Party: (i) sufficient written notice, of at least 30 days, to allow the Secured Party to timely pay any such maintenance fees or annuities which may become due on any Patents or Trademarks, or to file any affidavit or renewal with respect thereto, and (ii) a separate written power of attorney or other authorization to pay such maintenance fees, filing fees or annuities, or to file such affidavit or renewal, should such be necessary or desirable.

(i) **Secured Party's Right to Take Action.** If the Debtor fails to perform or observe any of its covenants or agreements set forth in this Section 3, and if such failure continues for a period of ten (10) calendar days after the Secured Party gives the Debtor written notice thereof (or, in the case of the agreements contained in subsection (h), immediately upon the occurrence of such failure, without notice or lapse of time), or if the Debtor notifies the Secured Party that it intends to abandon a Patent or Trademark which it is obligated to maintain pursuant to the terms of the Credit Agreement, the Secured Party may (but need not) perform or observe such covenant or agreement or take steps to prevent such intended abandonment on behalf and in the name, place and stead of the Debtor (or, at the Secured Party's option, in the Secured Party's own name) and may (but need not) take any and all other actions which the Secured Party may reasonably deem necessary to cure or correct such failure or prevent such intended abandonment.

(j) **Costs and Expenses.** Except to the extent that the effect of such payment would be to render any loan or forbearance of money usurious or otherwise illegal under any applicable law, the Debtor shall pay the Secured Party on demand the amount of all moneys expended and all costs and expenses (including reasonable attorneys' fees and disbursements) incurred by the Secured Party in connection with or as a result of the Secured Party's taking action under subsection (i) or exercising its rights under Section 6, together with interest

thereon from the date expended or incurred by the Secured Party at the Default Rate.

(k) **Power of Attorney.** To facilitate the Secured Party's taking action under subsection (i) and exercising its rights under Section 6, the Debtor hereby irrevocably appoints (which appointment is coupled with an interest) the Secured Party, or its delegate, as the attorney-in-fact of the Debtor with the right (but not the duty) from time to time to create, prepare, complete, execute, deliver, endorse or file, in the name and on behalf of the Debtor, any and all instruments, documents, applications, financing statements, and other agreements and writings required to be obtained, executed, delivered or endorsed by the Debtor under this Section 3 (including replacement Exhibits), or, necessary for the Secured Party, after an Event of Default, to enforce or use the Patents or Trademarks or to grant or issue any exclusive or non-exclusive license under the Patents or Trademarks to any third party, or to sell, assign, transfer, pledge, encumber or otherwise transfer title in or dispose of the Patents or Trademarks to any third party. The Debtor hereby ratifies all that such attorney shall lawfully do or cause to be done by virtue hereof. The power of attorney granted herein shall terminate upon the termination of the Credit Agreement as provided therein and the payment and performance of all Obligations.

(l) **Further Assurances.** The Debtor, upon the written request of the Secured Party, shall execute and deliver such further documents, as may be reasonably necessary to carry out the intent of this Agreement and to perfect and preserve the rights and interests of the Secured Party hereunder and the priority thereof.

4. **Debtor's Use of the Patents and Trademarks.** The Debtor shall be permitted to control and manage the Patents and Trademarks, including the right to exclude others from making, using or selling items covered by the Patents and Trademarks and any licenses thereunder, in the same manner and with the same effect as if this Agreement had not been entered into, so long as no Event of Default occurs and remains uncured.

5. **Events of Default.** Each of the following occurrences shall constitute an event of default under this Agreement (herein called "Event of Default"): (a) an Event of Default, as defined in the Credit Agreement, shall occur; or (b) the Debtor shall fail promptly to observe or perform any covenant or agreement herein binding on it; or (c) any of the representations or warranties contained in Section 3 shall prove to have been incorrect in any material respect when made.

6. **Remedies.** Upon the occurrence of an Event of Default and at any time thereafter, the Secured Party may, at its option, take any or all of the following actions:

(a) The Secured Party may exercise any or all remedies available under the Credit Agreement.

(b) The Secured Party may sell, assign, transfer, pledge, encumber or otherwise dispose of the Patents and Trademarks.

(c) The Secured Party may enforce the Patents and Trademarks and any licenses thereunder, and if Secured Party shall commence any suit for such enforcement, the Debtor shall, at the request of Secured Party, do any and all lawful acts and execute any and all proper documents required by Secured Party in aid of such enforcement.

7. Miscellaneous. This Agreement can be waived, modified, amended, terminated or discharged, and the Security Interest can be released, only explicitly in a writing signed by the Secured Party. A waiver signed by the Secured Party shall be effective only in the specific instance and for the specific purpose given. Mere delay or failure to act shall not preclude the exercise or enforcement of any of the Secured Party's rights or remedies. All rights and remedies of the Secured Party shall be cumulative and may be exercised singularly or concurrently, at the Secured Party's option, and the exercise or enforcement of any one such right or remedy shall neither be a condition to nor bar the exercise or enforcement of any other. All notices to be given to Debtor under this Agreement shall be given in the manner and with the effect provided in the Credit Agreement. The Secured Party shall not be obligated to preserve any rights the Debtor may have against prior parties, to realize on the Patents and Trademarks at all or in any particular manner or order, or to apply any cash proceeds of Patents and Trademarks in any particular order of application. This Agreement shall be binding upon and inure to the benefit of the Debtor and the Secured Party and their respective participants, successors and assigns and shall take effect when signed by the Debtor and delivered to the Secured Party, and the Debtor waives notice of the Secured Party's acceptance hereof. The Secured Party may execute this Agreement if appropriate for the purpose of filing, but the failure of the Secured Party to execute this Agreement shall not affect or impair the validity or effectiveness of this Agreement. A carbon, photographic or other reproduction of this Agreement or of any financing statement signed by the Debtor shall have the same force and effect as the original for all purposes of a financing statement. This Agreement shall be governed by the internal law of Arizona without regard to conflicts of law provisions. If any provision or application of this Agreement is held unlawful or unenforceable in any respect, such illegality or unenforceability shall not affect other provisions or applications which can be given effect and this Agreement shall be construed as if the unlawful or unenforceable provision or application had never been contained herein or prescribed hereby. All representations and warranties contained in this Agreement shall survive the execution, delivery and performance of this Agreement and the creation and payment of the Obligations.

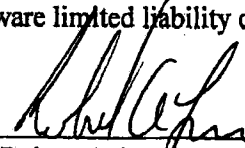
8. Prior Agreement. This Agreement amends and restates as of the date hereof, and continues the security interest granted in, the Patent and Trademark Security Agreement executed on or about February 6, 2004 by the Debtor and Wells Fargo Business Credit, Inc. (to whose interest the Secured Party has succeeded by merger).

THE PARTIES WAIVE ANY RIGHT TO TRIAL BY JURY IN ANY ACTION OR PROCEEDING BASED ON OR PERTAINING TO THIS AGREEMENT.

IN WITNESS WHEREOF, the parties have executed this Patent and Trademark Security Agreement as of the date written above.

FlipChip International, LLC
3701 E. University Blvd., Building B
Phoenix, Arizona 85035
Attn: Robert A. Forcier

FLIPCHIP INTERNATIONAL, LLC, a
Delaware limited liability company

By: 
Robert A. Forcier, Manager

Wells Fargo Business Credit, Inc.
Wells Fargo Plaza, MACS S4101-158
100 Washington Street, 15th Floor
Phoenix, AZ 85003
Attn: Daniel J. Barkosky

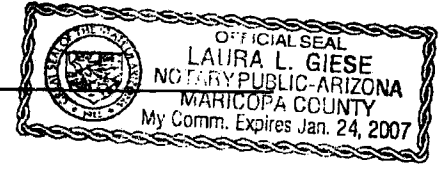
WELLS FARGO BANK, NATIONAL
ASSOCIATION, acting through its Wells
Fargo Business Credit operating division

By: _____
Daniel J. Barkosky, Vice President

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this 12th day of October, 2005, by Robert A. Forcier, Manager of FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company, on behalf of FlipChip International, LLC.

Laura L. Giese
Notary Public



My Commission Expires:

January 24, 2007

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of October, 2005, by Joseph A. Lisack, an Assistant Vice President of WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division, on behalf of the bank.

Notary Public

My Commission Expires:

IN WITNESS WHEREOF, the parties have executed this Patent and Trademark Security Agreement as of the date written above.

FlipChip International, LLC
3701 E. University Drive, Building B
Phoenix, Arizona 85035
Attn: Robert A. Forcier

FLIPCHIP INTERNATIONAL, LLC, a
Delaware limited liability company

By: _____
Robert A. Forcier, Manager

Wells Fargo Business Credit, Inc.
Wells Fargo Plaza, MACS S4101-158
100 Washington Street, 15th Floor
Phoenix, AZ 85003
Attn: Daniel J. Barkosky

WELLS FARGO BANK, NATIONAL
ASSOCIATION, acting through its Wells
Fargo Business Credit operating division

By: 
Daniel J. Barkosky, Vice President

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of October, 2005, by Robert A. Forcier, Manager of FLIPCHIP INTERNATIONAL, LLC, a Delaware limited liability company, on behalf of FlipChip International, LLC .

Notary Public

My Commission Expires:

STATE OF ARIZONA)
)ss
COUNTY OF MARICOPA)

The foregoing instrument was acknowledged before me this ___ day of October, 2005, by Joseph A. Lisack, an Assistant Vice President of WELLS FARGO BANK, NATIONAL ASSOCIATION, acting through its Wells Fargo Business Credit operating division, on behalf of the bank.

Daniel J Barkosky

Notary Public

My Commission Expires:

7/29/08



Amendment And Restated Patent And Trademark Security Agreement

EXHIBIT A

UNITED STATES ISSUED PATENTS

FlipChip Owned Patents

FlipChip Awarded Patents			
Patent #	Award Date	Filed	Title
6,287,893	9/11/01	7/13/98	Method for Forming Chip Scale Package
6,445,069	9/3/02	1/22/01	Electroless Ni/Pd/Au Metallization Structure for Copper Interconnect Substrate and Method Therefor
6,441,487	8/27/02	10/20/97	Chip Scale Package Using Large Ductile Solder Balls
6,578,755	6/17/03	9/22/00	Polymer Collar
6,750,135	06/15/04	06/20/01	Method For Forming Chip Scale Package
6,919,508	06/19/05	11/10/03	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing

Active Flip Chip (filings)			
Serial Number	Country	Filing Date	Title
09/575,298	US	5/19/00	Solder bar for High Power FlipChips
PCT/US04/31 732	International	09/27/04	Forming Partial-Depth Features In Polymer Film
10/672,201	US	09/26/03	Forming Partial-Depth Features In Polymer Film
PCT/US04/31 583	International	09/27/04	Wafer-Level Moat Structures
10/672,165	US	09/26/03	Wafer-Level Moat Structures
60/623,200	US	10/29/04	High Performance Chip Scale Package For Radio Frequency Devices
11/145,948	US	06/07/05	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing

Active Flip Chip (filings)			
Serial Number	Country	Filing Date	Title
60/646,743	US	01/25/05	High Sensitivity Thermopile Sensor Suitable For Direct Contact Temperature Measurements

FlipChip Owned Inactive Filings

Flip Chip inactive (filings)					
Serial Number	Country	Filing Date	Title	Author(s)	Description
PCT/US98/22071	International	10/18/98	Chip Scale Package Using Large Ductile Solder Balls	Peter Elenius; Harry Hollack	International versions of issued US patents
PCT/US01/15928	International	5/17/01	Solder bar for High Power FlipChips	Peter Elenius; Hong Yang	Method for forming structures for heat dissipation
PCT/US01/29509	International	09/21/01	Polymer Collar For Solder Bumps	Peter Elenius, Deok Hong Kim	
PCT/US02/01655	International	1/18/02	ENi/Pd/Au Metallization structure for Cu Interconnect substrate and method Therfor	Jamin Ling; Dave Charles Stepniak	ENi/Pd/Au Metallization structure for Cu Interconnect substrate and method Therfor

Licensed Patents

FlipChip holds the licenses to the patents below (the "Delphi Patents") from Delco Electronics Corporation and/or Delphi Corporation (together, "Delphi"). The licenses for the Delphi Patents were obtained under the Technology Transfer Agreement, dated as of February 28, 1996, between Delco Electronics Corporation and Flip Chip Technologies, LLC, as amended (the "Technology Transfer Agreement") and is considered "Technology" as defined therein.

Delco/Delphi Awarded Patents and IP (filings, ideas)			
Patent #	Award Date	Filed	Title
5,547,740	8/20/96	3/23/95	Solderable Contacts for Flip Chip Integrated Circuit Devices
5,938,862	8/17/99	4/3/98	Fatigue-Resistant Lead Free Alloy
5,607,099	3/4/97	4/24/95	Solder Bump transfer device for Flip Chip Integrated Circuit Devices
5,632,667	5/27/97	6/29/95	No Coat Backside Wafer Grinding Process
5,803,340	9/8/98	9/29/95	Composite Solder Paste for Flip Chip Bumping
6,184,581	2/6/01	11/24/97	Solder Bump Input/Output pad for Surface mount circuit device

Delco/Delphi Awarded Patents and IP (filings, ideas)			
Patent #	Award Date	Filed	Title
5,891,756	4/6/99	6/27/97	Process for Converting a Wire Bond Pad to a Flip Chip Bump Pad formed thereby
6,251,501	6/26/01	3/29/99	Surface Mount Circuit Device and Solder Bumping Method Therefor
6,281,106	8/28/01	11/25/99	Method of Solder Bumping a Circuit Component
6,375,062	4/23/02	11/6/00	Surface Bumping Method and Structure Formed Thereby
6,619,536	9/16/03	2/15/02	Solder paste composition
6,570,260	5/27/03	2/15/02	Solder paste composition

The patent application (the "Application") listed below is licensed from Delphi. The Application was obtained under the Technology Transfer Agreement and is considered Technology thereunder.

Active (filings)			
Serial Number	Country	Filing Date	Title
6,811,892	US	8/22/02	Lead based solder Alloys containing copper
08/511,766	US	Unknown	Method for Flip Chip Solder Bump Formulation with Solder Paste using a CFC-Free Photoresist Film

FOREIGN ISSUED PATENTS

FlipChip Owned Foreign Patents

Flip Chip Awarded Patents			
Patent #	Award Date	Filed	Title
NI-171691	2/11/03	09/21/01	Polymer Collar

Active Flip Chip (filings)			
Serial Number	Country	Filing Date	Title

Active Flip Chip (filings)

Serial Number	Country	Filing Date	Title
2000-517447	Japan	10/19/98	Chip Scale Package Using Large Ductile Solder Balls
98953717.0	EPO	10/19/98	Chip Scale Package Using Large Ductile Solder Balls
10-2000-7004263	Korea	10/19/98	Chip Scale Package Using Large Ductile Solder Balls
1971260.3	EPO	9/21/01	Polymer Collar for Solder Bumps
10-2003-7004188	Korea	9/21/01	Polymer Collar for Solder Bumps
1935623.7	EPO	5/17/01	Solder bar for High Power FlipChips

EXHIBIT B

Trademarks					
Serial Number	Country	Filing Date	Word Mark	Owner	Status
78/168486	US	09/27/02	Spheron	FlipChip International, LLC	Registered
75/347767	US	10/09/01	UltraCSP	FlipChip International, LLC	Registered
78/439,264	US	6/22/04	FOC Flex-On Cap	FlipChip International, LLC	Received Notices of Allowance
78/428,935	US	6/02/04	Lifestyle	FlipChip International, LLC	Received Notices of Allowance
78/428,930	US	6/02/04	FlipChip International	FlipChip International, LLC	Registered